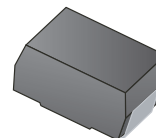


RoHS Compliant Product
A suffix of "-C" specifies halogen & lead-free

FEATURES

- Low Profile Package
- Ideal for Automated Placement
- Glass Passivated Chip Junction
- High Forward Surge Capability
- Super Fast Reverse Recovery Time
- Meets MSL Level 1, per J-STD-020, LF Maximum Peak of 260°C

SMA



MECHANICAL DATA

- Epoxy: UL94V-0 Rate Flame Retardant
- Terminals: Tin Plated Leads, Solderable per J-STD-002 and JESD22-B102
- Polarity: Cathode line denotes the cathode end
- Mounting Position: Any

PACKAGE INFORMATION

Package	MPQ	Leader Size
SMA	5K	13 inch

ORDER INFORMATION

Part Number	Type
EU11A-C~EU14A-C	Lead (Pb)-free and Halogen-free



MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS ($T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Part Number				Unit
		EU11A-C	EU12A-C	EU13A-C	EU14A-C	
Repetitive Peak Reverse Voltage	V_{RRM}	50	100	200	400	V
Maximum RMS Voltage	V_{RMS}	35	70	140	280	
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	
Average Rectified Output Current @60Hz sine wave, Resistance load, T_L	I_o	1				A
Surge (Non-repetitive) Forward Current	60Hz half-sine wave	30				A
	1ms square wave	60				
Maximum Instantaneous Forward Voltage @ $I_F=1A$	V_F	0.92			1.25	V
Maximum DC Reverse Current @Rated DC Blocking Voltage	$T_J=25^\circ\text{C}$	5				μA
	$T_J=125^\circ\text{C}$	50				
Maximum Reverse Recovery Time	T_{RR}	25				nS
Typical Junction Capacitance	C_J	17			15	pF
Typical Thermal Resistance ¹	$R_{\theta JA}$	70				$^\circ\text{C/W}$
	$R_{\theta JL}$	25				
Operating & Storage Temperature Range	T_J, T_{STG}	-55~150				$^\circ\text{C}$

Note:
 1. Thermal resistance from junction to ambient and from junction to lead mounted on P.C.B. with 0.2" x 0.2" (5mm x 5mm) copper pad areas.

CHARACTERISTICS CURVE

FIG.1: Io-TL Curve

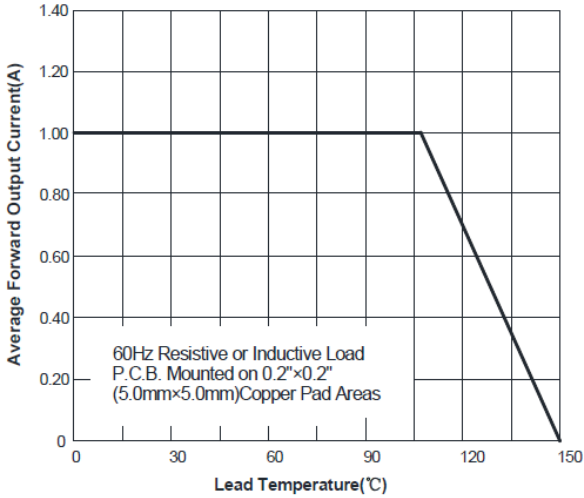


FIG.2: Forward Surge Current Capability

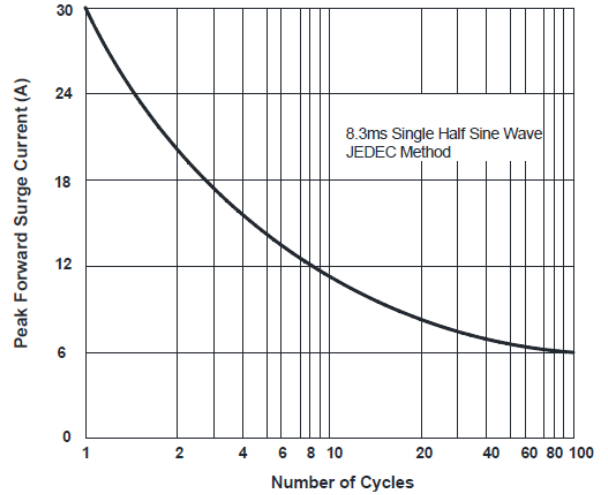


FIG.3: Typical Forward Characteristics

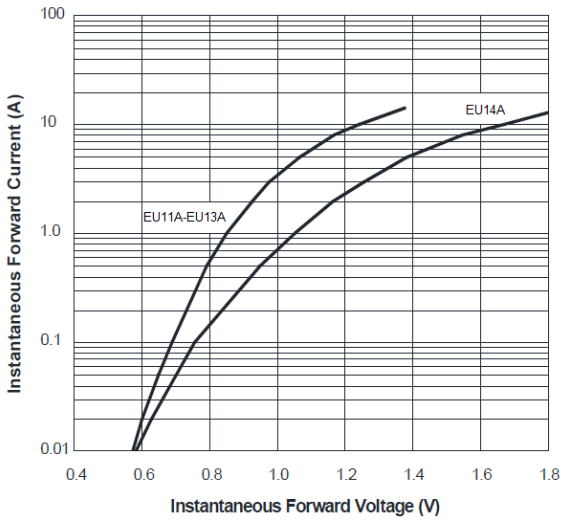


FIG.4: Typical Reverse Characteristics

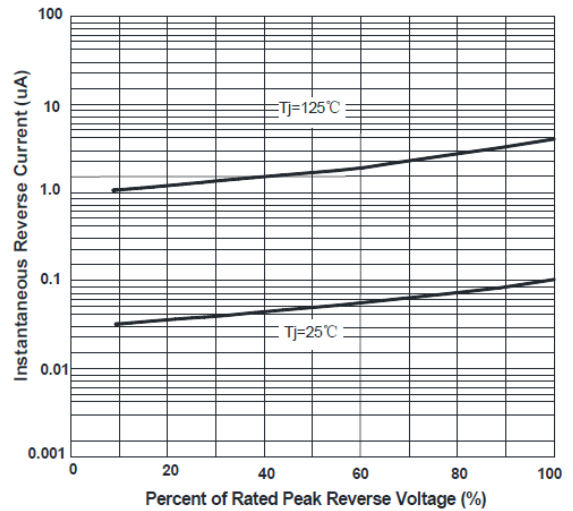
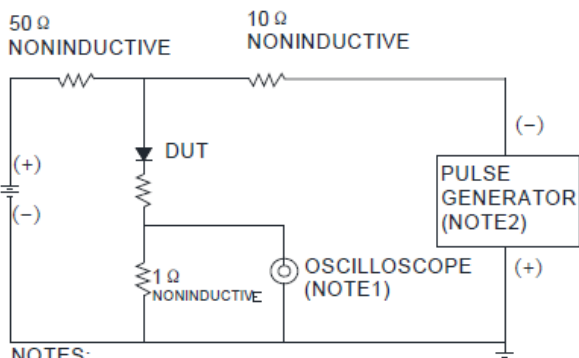
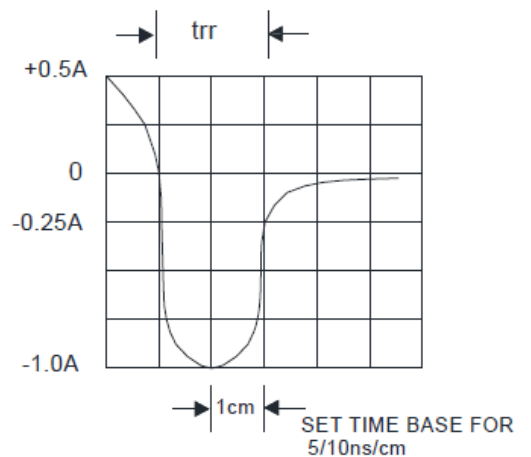


FIG.5: Diagram of circuit and Testing wave form of reverse recovery time

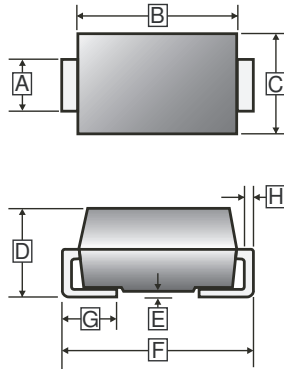


- NOTES:
1. Rise Time=7ns max .Inpot Impedance=1M Ω 22pf
2. Rise Time=10ns max.Source Impedance=50 Ω



PACKAGE OUTLINE DIMENSIONS

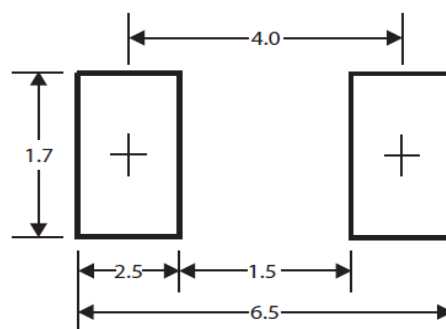
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REF.	Millimeter	
	Min.	Max.
A	1.23	1.65
B	3.99	4.75
C	2.30	2.90
D	1.90	2.62
E	-	0.3
F	4.70	5.28
G	0.75	1.52
H	0.15	0.31

MOUNTING PAD LAYOUT

SMA



*Dimensions in millimeters